

## SINGLE-CHIP USB-TO-SPI BRIDGE

### Single-Chip USB-to-SPI Bridge

- Integrated clock; no external crystal required
- Integrated USB transceiver; no external resistors required
- Integrated 348 Byte one-time programmable ROM for product customization
- On-chip power-on reset circuit
- On-chip voltage regulator: 3.45 V output
- Uses USB Bulk Mode transactions for high throughput
  - Configurable priority for reads and writes

### USB Peripheral Function Controller

- USB Specification 2.0 compliant; full-speed (12 Mbps)
- USB suspend states supported and indicated via suspend output pins

### USB Interface

- Windows 8<sup>®</sup>, 7<sup>®</sup>, Vista<sup>®</sup>, and XP<sup>®</sup>
- Open access to interface specification

### Windows Libraries

- APIs for quick application development
- Supports Windows 8<sup>®</sup>, 7<sup>®</sup>, Vista<sup>®</sup>, and XP<sup>®</sup> (SP2 & SP3)

### Packages

- RoHS-compliant 24-QFN package (4x4 mm)

### SPI Controller

- 3 or 4-wire master mode operation
- Configurable clock rate
  - 12 MHz, 6 MHz, 3 MHz, 1.5 MHz, 750 kHz, 375 kHz, 187.5 kHz, 93.75 kHz
- Clock phase and polarity control
- Chip select mode and toggle
- Programmable SPI delay (post-assert, inter-byte, pre-deassert)

### 11 Configurable GPIO Pins with Alternate Functions

- Usable as inputs, open-drain outputs, or push-pull outputs
- Up to 11 chip select outputs
- Ready-to-read pin allows for external signal to trigger SPI read operations
- Ability to count edges or pulses using the Event Counter
- Up to 11 USB remote wakeup sources
- SPI activity indication (toggles to indicate SPI activity)
- Configurable clock output (93.75 kHz to 24 MHz)

### Supply Voltage

- Self powered (regulator disabled): 3.0 to 3.6 V
- Self powered (regulator enabled): 3.0 to 5.25 V
- USB bus powered: 4.0 to 5.25 V
- I/O voltage: 1.8 V to V<sub>DD</sub>

### Ordering Part Numbers

- CP2130-F01-GM

Temperature Range: -40 to +85 °C

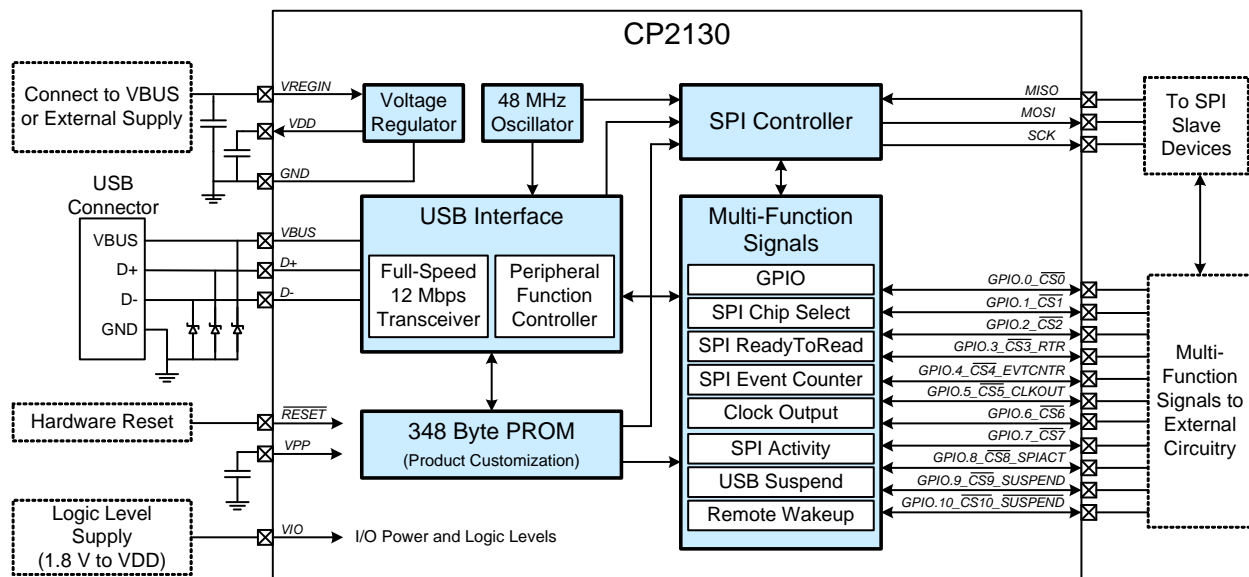


Figure 1. Example System Diagram



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## 1. System Overview

The CP2130 is a highly-integrated USB-to-SPI bridge controller providing a simple solution for bridging a Universal Serial Bus (USB) host to a Serial Peripheral Interface (SPI) bus using a minimum of components and PCB space. The CP2130 includes a USB 2.0 full-speed controller, USB transceiver, oscillator, one-time programmable (OTP) ROM, and a SPI controller in a compact 4 x 4 mm QFN24 package (sometimes called “MLF” or “MLP”).

The on-chip, OTP ROM provides the option to customize the USB Vendor ID, Product ID, Manufacturer String, Product Description String, Power Descriptor, Device Release Number, Device Serial Number, and GPIO configuration as desired for OEM applications.

The CP2130 uses a Silicon Labs vendor-specific USB protocol using control and bulk transfers which is supported by most operating systems through the use of generic USB drivers and interface libraries. A custom driver typically does not need to be developed for this device. Windows applications communicate with the CP2130 through a Windows DLL which is provided by Silicon Labs that communicates with the Microsoft WinUSB driver via a WinUSB DLL. The interface specification for the CP2130 is also available to enable development of an API for any operating system that supports control and bulk transfers over USB.

The CP2130 SPI implements the standard signals, including SCK, MISO, MOSI,  $\overline{CS}$ , as well as a ready-to-read (RTR) hardware handshaking input, so existing system firmware does not need to be modified. The SPI capabilities of the CP2130 include fixed SPI clock rates ranging from 93.75 kHz to 12 MHz, configurable clock phase, configurable clock polarity, adjustable SPI delays, and up to 11 configurable chip select signals.

Any of the multi-purpose pins not used as chip select signals may instead be used as GPIO signals that are user-defined. The GPIO signals may also be configured to initiate a USB remote wakeup event on GPIO state change, which allows the CP2130 to wake a USB host from sleep mode. Eight of the GPIO signals support alternate features including ready-to-read (RTR) handshaking, a configurable event counter, a configurable clock output (93.75 kHz to 24 MHz), SPI activity LED toggle, and USB suspend indicators. Support for I/O interface voltages down to 1.8 V is provided via a  $V_{IO}$  pin.

An evaluation kit for the CP2130 (Part Number: CP2130EK) is available. It includes a CP2130-based USB-to-SPI evaluation board with SPI slave devices such as an EEPROM and ADC as well as connections for an external CP2400 LCD controller EVB and SPI monitor. The kit also includes a Windows DLL and test application, USB cables, and full documentation. See [www.silabs.com](http://www.silabs.com) for the latest application notes and product support information for the CP2130. Contact a Silicon Labs sales representatives or go to [www.silabs.com](http://www.silabs.com) to order the CP2130 Evaluation Kit.

## 2. Electrical Characteristics

**Table 1. Global DC Electrical Characteristics**
 $V_{DD} = 3.0$  to  $3.6$  V,  $-40$  to  $+85$  °C unless otherwise specified.

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Digital Supply Voltage	$V_{DD}$		3.0	—	3.6	V
Digital Port I/O Supply Voltage	$V_{IO}$		1.8	—	$V_{DD}$	V
Specified Operating Temperature Range	$T_A$		-40	—	+85	°C
Thermal Resistance <sup>1</sup>	$\theta_{JA}$		—	28	—	°C/W
<b>Supply Current</b>						
USB Suspended <sup>2</sup>	$I_{REGIN}$	Bus Powered; Regulator enabled	—	170	360	$\mu$ A
		Self Powered; Regulator disabled; $V_{DD} = 3.0$ V	—	170	290	$\mu$ A
		Self Powered; Regulator disabled; $V_{DD} = 3.3$ V	—	210	330	$\mu$ A
USB Normal; SPI Idle <sup>2</sup>		Bus Powered; Regulator enabled	—	14.4	18.8	mA
		Self Powered; Regulator disabled; $V_{DD} = 3.0$ V	—	13.8	18.1	mA
		Self Powered; Regulator disabled; $V_{DD} = 3.3$ V	—	14.1	18.4	mA
USB Normal; SPI Active <sup>2</sup>		Bus Powered; Regulator enabled	—	17.8	23.2	mA
		Self Powered; Regulator disabled; $V_{DD} = 3.0$ V	—	16.6	21.7	mA
		Self Powered; Regulator disabled; $V_{DD} = 3.3$ V	—	17.1	22.2	mA
USB Pull-up <sup>3</sup>	$I_{PU}$		—	200	230	$\mu$ A
<b>Notes:</b>						
1. Thermal resistance assumes a multi-layer PCB with any exposed pad soldered to a PCB pad.						
2. USB Pull-up current should be added for total supply current. USB normal and suspended supply current is current flowing into $V_{REGIN}$ . USB normal and suspended supply current is guaranteed by characterization.						
3. The USB Pull-up supply current values are calculated values based on USB specifications. USB Pull-up supply current is current flowing from VDD to GND through USB pull-down/pull-up resistors on D+ and D-.						

**Table 2. SPI, Port I/O, and Suspend I/O DC Electrical Characteristics**

$V_{IO} = 1.8$  to  $3.6$  V,  $-40$  to  $+85$  °C unless otherwise specified.

Parameters	Symbol	Test Condition	Min	Typ	Max	Unit
Output High Voltage	$V_{OH}$	$I_{OH} = -10 \mu A$ , Port I/O push-pull $I_{OH} = -3$ mA, Port I/O push-pull $I_{OH} = -10$ mA, Port I/O push-pull	$V_{IO} - 0.1$ $V_{IO} - 0.2$ —	— — $V_{IO} - 0.4$	— — —	V
Output Low Voltage	$V_{OL}$	$I_{OL} = 10 \mu A$ $I_{OL} = 8.5$ mA $I_{OL} = 25$ mA	— — —	— — 0.6	0.1 0.4 —	V
Input High Voltage	$V_{IH}$		$0.7 \times V_{IO}$	—	—	V
Input Low Voltage	$V_{IL}$		—	—	0.6	V
Input Leakage Current	$I_L$	Weak Pull-Up On, $V_{IN} = 0$ V	—	25	50	$\mu A$
Maximum Input Voltage		Open drain, logic high (1)	—	—	5.8	V

**Table 3. Reset Electrical Characteristics**

$-40$  to  $+85$  °C unless otherwise specified.

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
$V_{DD}$ Ramp Time	$t_{RMP}$	Time to $V_{DD} \geq 2.7$ V	—	—	1	ms
$\overline{RST}$ Input High Voltage	$V_{IHRESET}$		$0.75 \times V_{IO}$	—	—	V
$\overline{RST}$ Input Low Voltage	$V_{ILRESET}$		—	—	0.6	V
$\overline{RST}$ Low Time to Generate a System Reset	$t_{RSTL}$		15	—	—	$\mu s$

**Table 4. Voltage Regulator Electrical Specifications**

$-40$  to  $+85$  °C unless otherwise specified.

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Input Voltage Range <sup>1</sup>	$V_{REGIN}$	Regulator Enabled	$V_{DD} + V_{DO}$	—	5.25	V
Output Voltage <sup>2</sup>	$V_{DDOUT}$	Output Current = 1 to 100 mA	3.3	3.45	3.6	V
VBUS Detection Input Threshold	$V_{BUSTH}$		2.5	—	—	V
Dropout Voltage	$V_{DO}$	$1 \text{ mA} \leq I_{DD} \leq 100 \text{ mA}$	—	1	—	mV / mA
Bias Current			—	—	120	$\mu A$

**Notes:**

1. Input range specified for regulation. When the internal regulator is not used, should be tied to  $V_{DD}$ .
2. The maximum regulator supply current is 100 mA. This includes the supply current of the CP2130.

**Table 5. GPIO Output Specifications**

-40 to +85 °C unless otherwise specified.

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
GPIO.5 Clock Output*	$F_{CLKOUT}$	$F_{CLKOUT} = \text{configured frequency}$	$F_{CLKOUT} \times 0.985$	$F_{CLKOUT}$	$F_{CLKOUT} \times 1.015$	Hz
SPI Activity Toggle Rate	$F_{SPIACT}$		—	10	—	Hz

**\*Note:** The clock output frequency is configurable from 93.75 kHz to 24 MHz.

**Table 6. USB Transceiver Electrical Characteristics\*** $V_{DD} = 3.0 \text{ V to } 3.6 \text{ V}$ , -40 to +85 °C unless otherwise specified.

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
<b>Transmitter</b>						
Output High Voltage	$V_{OH}$		2.8	—	—	V
Output Low Voltage	$V_{OL}$		—	—	0.8	V
Output Crossover Point	$V_{CRS}$		1.3	—	2.0	V
Output Impedance	$Z_{DRV}$	Driving High Driving Low	— —	36 36	— —	$\Omega$
Pull-up Resistance	$R_{PU}$	Full Speed (D+ Pull-up)	1.425	1.5	1.575	k $\Omega$
Output Rise Time	$T_R$	Full Speed	4	—	20	ns
Output Fall Time	$T_F$	Full Speed	4	—	20	ns
<b>Receiver</b>						
Differential Input Sensitivity	$V_{DI}$	$ (D+) - (D-) $	0.2	—	—	V
Differential Input Common Mode Range	$V_{CM}$		0.8	—	2.5	V
Input Leakage Current	$I_L$	Pullups Disabled	—	<1.0	—	$\mu\text{A}$

**\*Note:** Refer to the USB Specification for timing diagrams and symbol definitions.

**Table 7. OTP ROM Electrical Characteristics**

-40 to +85 °C unless otherwise specified.

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Digital Port I/O Supply Voltage During Programming	$V_{IO}$		3.3	—	$V_{DD}$	V
Voltage on $V_{PP}$ with respect to GND during a programming operation	$V_{PP}$	$V_{IO} \geq 3.3 \text{ V}$	5.75	—	$V_{IO} + 3.6$	V
Capacitor on $V_{PP}$ for In-system Programming			—	4.7	—	$\mu\text{F}$

**Table 8. Thermal Characteristics**

Parameter	Symbol	Min	Typ	Max	Unit
Thermal Resistance*	$\theta_{JA}$	—	28	—	°C/W

**\*Note:** Thermal resistance assumes a multi-layer PCB with any exposed pad soldered to a PCB pad.

**Table 9. Absolute Maximum Ratings\***

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Ambient Temperature under Bias	$T_{BIAS}$		-55	—	125	°C
Storage Temperature	$T_{STG}$		-65	—	150	°C
Voltage on $\overline{RST}$ , GPIO, or SPI Pins with respect to GND		$V_{IO} \geq 2.2\text{ V}$ $V_{IO} < 2.2\text{ V}$	-0.3 -0.3	— —	5.8 $V_{IO} + 3.6$	V
Voltage on VBUS with respect to GND	$V_{BUS}$	$V_{DD} \geq 3.0\text{ V}$ $V_{DD}$ not powered	-0.3 -0.3	— —	5.8 $V_{DD} + 3.6$	V
Voltage on $V_{DD}$ or $V_{IO}$ with respect to GND	$V_{DD}$		-0.3	—	4.2	V
Maximum Total Current through $V_{DD}$ , $V_{IO}$ , REGIN, and GND			—	—	500	mA
Maximum Output Current Sunk by $\overline{RST}$ or any I/O pin			—	—	100	mA

**\*Note:** Stresses above those listed may cause permanent damage to the device. This is a stress rating only, and functional operation of the devices at or exceeding the conditions in the operation listings of this specification is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.



### 3. USB Function Controller and Transceiver

The Universal Serial Bus (USB) function controller in the CP2130 is a USB 2.0-compliant, full-speed device with integrated transceiver and on-chip matching and pullup resistors. The USB function controller manages all data transfers between the USB and the SPI bus as well as command requests generated by the USB host and commands for controlling the function of the SPI and GPIO pins.

The USB Suspend and Resume modes are supported for power management of both the CP2130 device as well as external circuitry. The CP2130 enters Suspend mode when Suspend signaling is detected on the bus. Upon entering Suspend mode, the Suspend signals are asserted. The Suspend signals are also asserted after a CP2130 reset until device configuration and USB Enumeration is complete. SUSPEND is logic high when the device is in the Suspend state, and logic low when the device is in normal mode. The SUSPEND pin has the opposite logic value of the SUSPEND pin.

The CP2130 exits Suspend mode when any of the following occur: Resume signaling is detected or generated, a USB Reset signal is detected, the configured GPIO wakeup sources do not match the configured latch value, or a device reset occurs. SUSPEND and SUSPEND are weakly pulled to VIO in a high impedance state during a CP2130 reset. If this behavior is undesirable, a strong pull-down (10 k $\Omega$ ) can be used to ensure SUSPEND remains low during reset.

The CP2130 can be configured to use any of the GPIO pins as a remote wakeup source. While suspended, if any of the pins configured as a wakeup source does not match the configured wakeup match value, then the CP2130 will send remote wakeup signaling to the USB host. If the host has configured the CP2130 to enable remote wakeup, then the host will send resume signaling to the CP2130 and the device will exit Suspend mode.

The logic level and output mode (push-pull or open-drain) of various pins during USB Suspend is configurable in the OTP ROM. See Section 6 for more information.

## 4. Serial Peripheral Interface (SPI)

The CP2130 Serial Peripheral Interface (SPI) provides access to a flexible, full-duplex synchronous serial bus. The CP2130 can operate as a master device in both 3-wire or 4-wire modes, and supports multiple slaves. Any of the 11 GPIO pins may be configured as chip select master outputs to select multiple SPI slave devices.

### 4.1. Signal Descriptions

The four signals used by SPI (MOSI, MISO, SCK,  $\overline{CS}$ ) are described below.

#### 4.1.1. Master Out, Slave In (MOSI)

The master-out, slave-in (MOSI) signal is an output from a master device and an input to slave devices. It is used to serially transfer data from the master to the slave. Data is transferred most-significant bit first.

#### 4.1.2. Master In, Slave Out (MISO)

The master-in, slave-out (MISO) signal is an output from a slave device and an input to the master device. It is used to serially transfer data from the slave to the master. Data is transferred most-significant bit first.

#### 4.1.3. Serial Clock (SCK)

The serial clock (SCK) signal is an output from the master device and an input to slave devices. It is used to synchronize the transfer of data between the master and slave on the MOSI and MISO lines. Since the CP2130 always acts as a SPI master, it always drives SCK.

#### 4.1.4. Chip Select ( $\overline{CS0}$ - $\overline{CS10}$ )

The CP2130 may be used to control up to 11 different SPI slave devices using GPIO pins configured in chip select output mode. Chip select signals are active low.

See Figure 2 and Figure 3 for typical connection diagrams of the various operational modes.

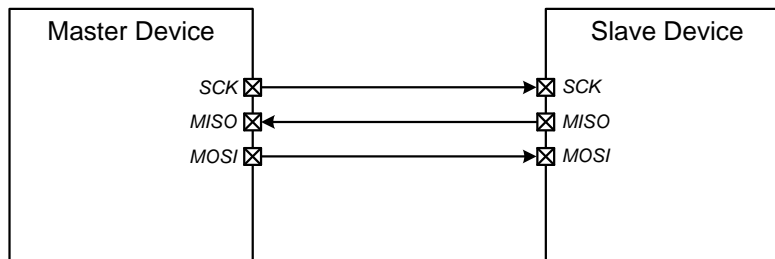


Figure 2. 3-Wire Single Master and 3-Wire Single Slave Mode Connection Diagram

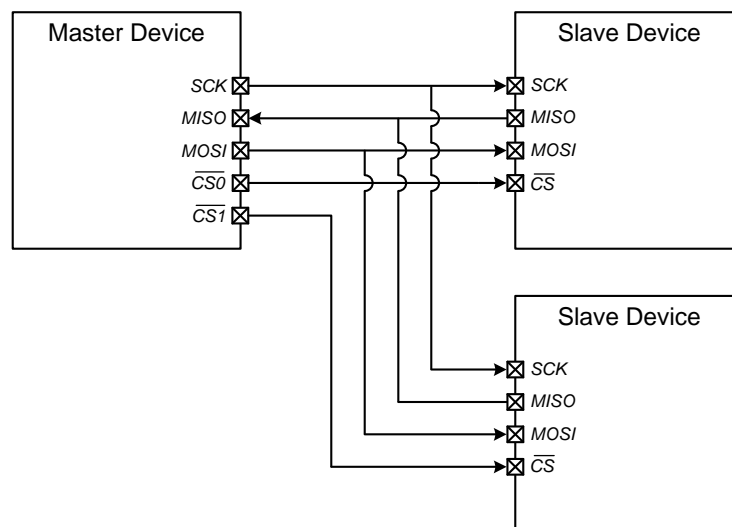


Figure 3. 4-Wire Single Master Mode and 4-Wire Slave Mode Connection Diagram

## 4.2. Data Throughput

SPI read and write data transfer throughput can be affected by many factors including USB host performance, host driver and PC application performance, SPI clock rate, and data transfer size. Also USB bulk transfers are limited by available bandwidth on the bus; increased traffic on the bus may decrease SPI throughput. Additionally, the CP2130 can be configured to operate in high-priority write or high-priority read mode. The priority mode is configured in the OTP ROM. The CP2130 has two independent USB endpoints used for bulk data transfers. The first endpoint is double buffered whereas the second endpoint is single buffered. Each endpoint is used for only a single direction. A USB IN transfer is data transferred from the device to the host. A USB OUT transfer is data transferred from the host to the device. More information about the USB interface can be found in application note, “AN792: CP2130 Interface Specification”. By default, the CP2130 is configured in high-priority write mode, in which the double-buffered endpoint is used for OUT transfers and the single-buffered endpoint is used for IN transfers. Conversely, when the CP2130 is configured in high-priority read mode, the double-buffered endpoint is used for IN transfers and the single-buffered endpoint is used for OUT transfers.

Table 10 below shows the CP2130 typical SPI throughput in high-priority write and high-priority read modes using a 64-bit PC.

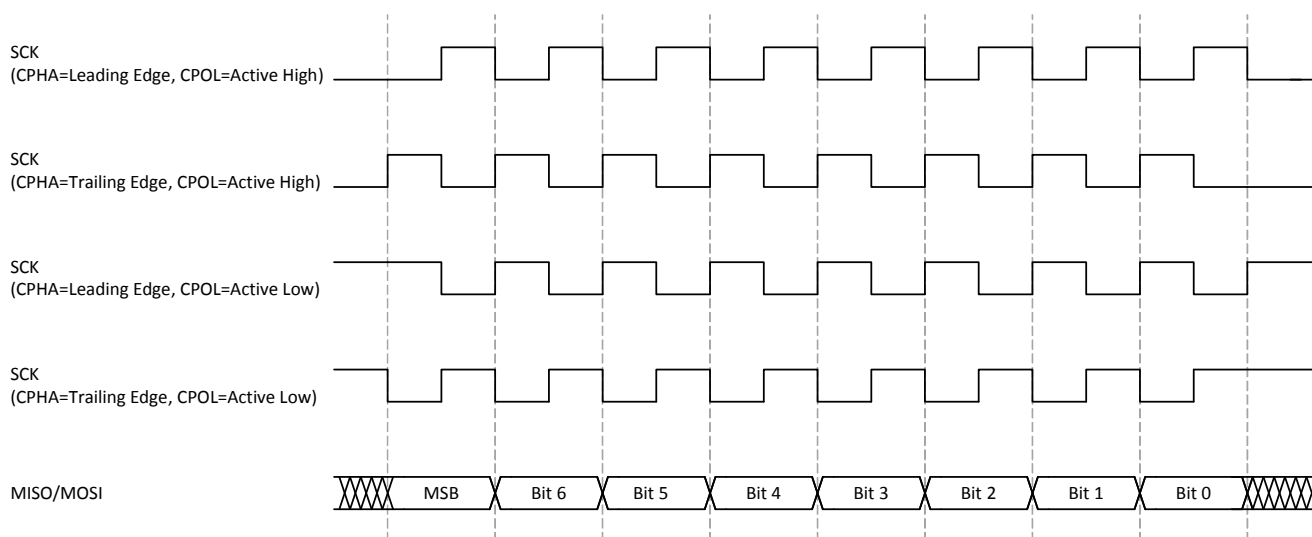
**Table 10. Typical SPI Throughput**

Device Configuration	Conditions	Write Throughput	Read Throughput	WriteRead Throughput	Units
High-Priority Write Mode	F <sub>SCK</sub> = 12 MHz; Block Size = 64 KB	4.9	4.6	3.5	Mbps
High-Priority Read Mode		4.2	6.6	2.9	Mbps

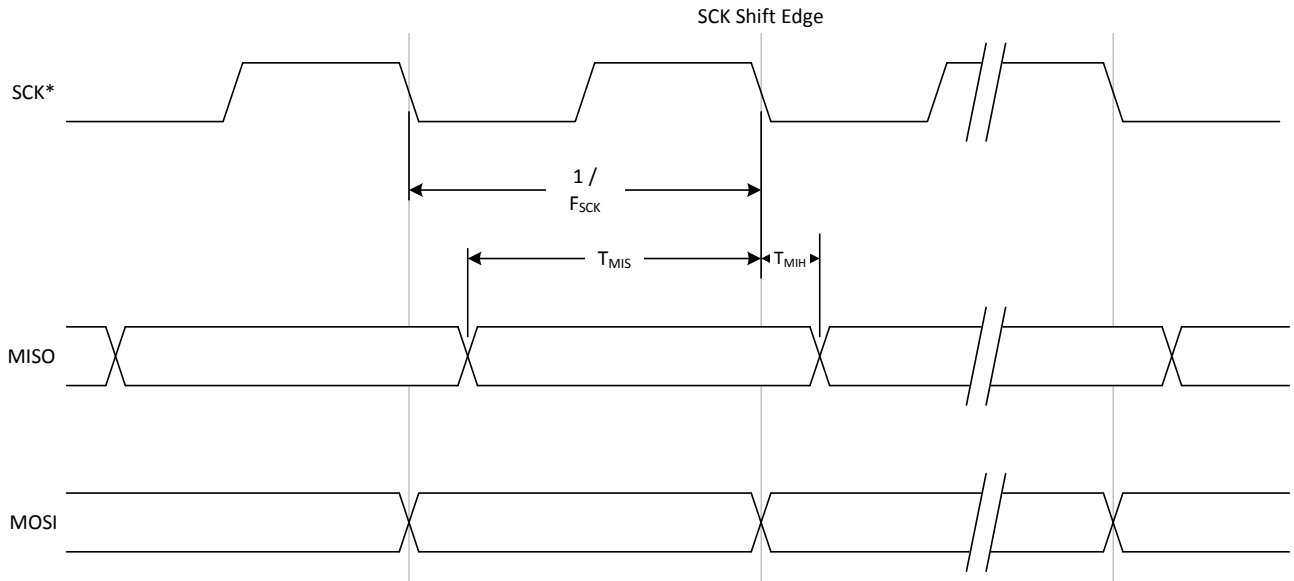
## 4.3. Serial Clock Phase and Polarity

Four combinations of serial clock phase and polarity can be selected using SPI control commands over the USB interface. The clock phase (CPHA) specifies which clock edge is used to latch the data. The clock polarity (CPOL) selects between an active-high or active-low clock. Both master and slave devices must be configured to use the same clock phase and polarity. The clock and data line relationships are shown in Figure 4.

The SPI clock field of the SPI control command controls the master mode serial clock frequency. The clock frequency is restricted to discrete values between 93.8 kHz and 12 MHz.

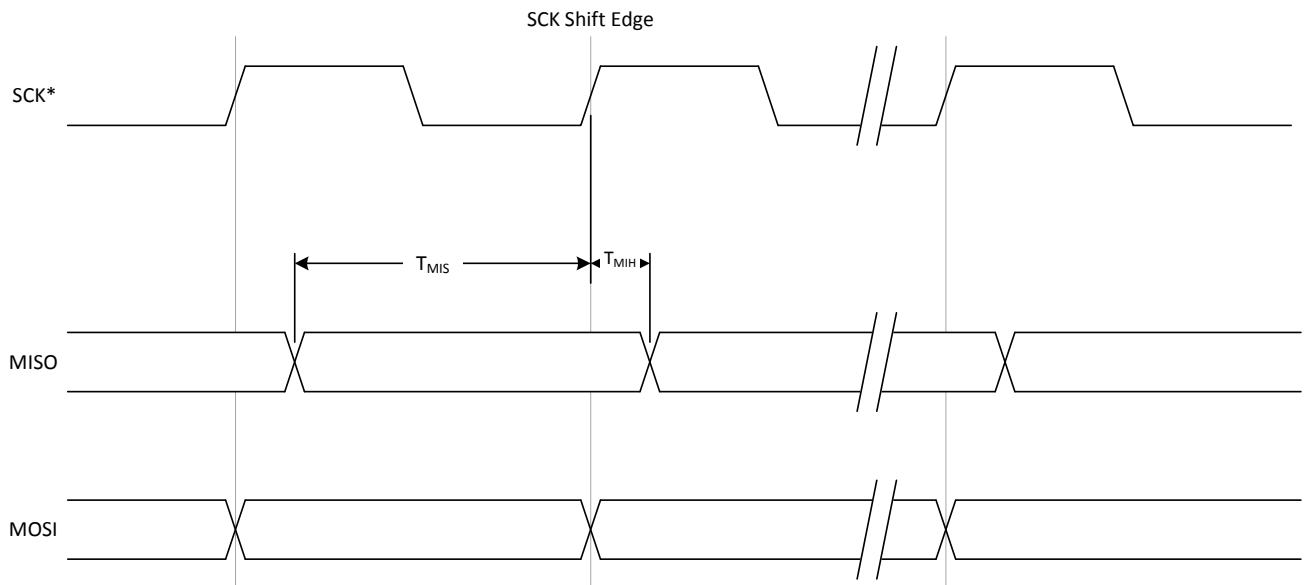


**Figure 4. Data/Clock Timing**



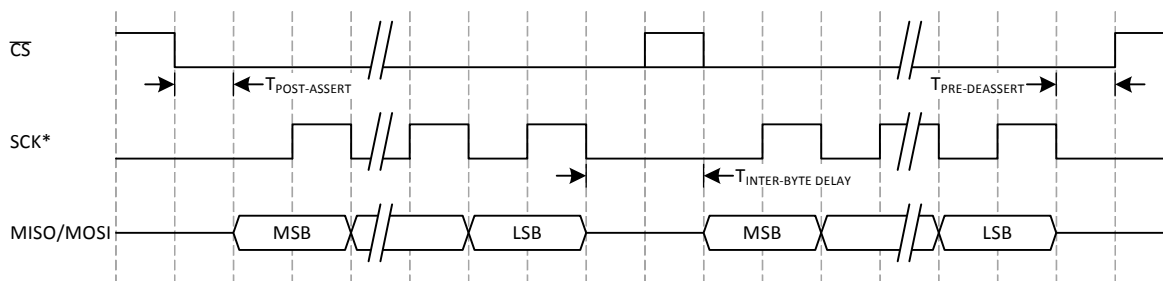
\* SCK is shown for CPOL = Active High. SCK is the opposite polarity for CPOL = Active Low.

**Figure 5. SPI Master Timing (CPHA=Leading Edge)**



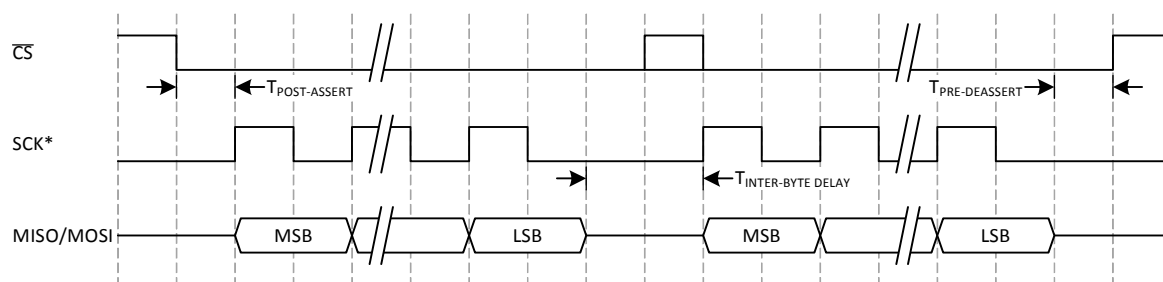
\* SCK is shown for CPOL = Active High. SCK is the opposite polarity for CPOL = Active Low.

**Figure 6. SPI Master Timing (CPHA=Trailing Edge)**



\* SCK is shown for CPOL = Active High. SCK is the opposite polarity for CPOL = Active Low.

Figure 7. SPI Delays (CPHA = Leading Edge)



\* SCK is shown for CPOL = Active High. SCK is the opposite polarity for CPOL = Active Low.

Figure 8. SPI Delays (CPHA = Trailing Edge)

Table 11. SPI Timing Parameters<sup>1</sup>

Parameter	Symbol	Min	Typ	Max	Units
SCK Frequency	$F_{SCK}$		12 MHz 6 MHz 3 MHz 1.5 MHz 750 kHz 375 kHz 187.5 kHz 93.75 kHz		
MISO Valid to SCK Shift Edge	$T_{MIS}$	41.15	—	—	ns
SCK Shift Edge to MISO Change	$T_{MIH}$	0	—	—	ns
Post-Assert SPI Delay <sup>2</sup>	$T_{POST-ASSERT}$		N x 10		$\mu$ s
Inter-Byte SPI Delay <sup>2</sup>	$T_{INTER-BYTE}$		N x 10		$\mu$ s
Pre-Deassert SPI Delay <sup>2</sup>	$T_{PRE-DEASSERT}$		N x 10		$\mu$ s
<b>Notes:</b>					
1. See Figures 5–8.					
2. N = user-specified delay values, where $\{0 \leq N \leq 65535\}$ .					

## 5. GPIO Pins

The CP2130 supports 11 user-configurable GPIO pins. Each of these GPIO pins are usable as inputs, open-drain outputs, or push-pull outputs. Each GPIO pin may also be configured for use as SPI chip select signals for up to 11 different SPI slaves. Six of these GPIO pins also have alternate functions which are listed in Table 12. More information regarding the configuration and usage of these pins is available in application note, “AN721: CP21xx Customization Guide” available on the Silicon Labs website.

**Table 12. GPIO Pin Alternate Functions**

GPIO Pin	Alternate Function
GPIO.3	Ready-to-Read (RTR)
GPIO.4	Event Counter
GPIO.5	Clock Output
GPIO.8	SPI Activity
GPIO.9	SUSPEND
GPIO.10	$\overline{\text{SUSPEND}}$

The default configuration for all of the GPIO pins is provided in Table 13. The configuration of the pins is one-time programmable for each device. See Section 6 for more information about programming the GPIO pin functionality.

**Table 13. GPIO Pin Default Configuration**

GPIO Pin	Default Function	GPIO Pin	Default Function
GPIO.0	CS0 (Push-Pull Output)	GPIO.6	GPIO (Input)
GPIO.1	CS1 (Push-Pull Output)	GPIO.7	GPIO (Push-Pull Output)
GPIO.2	CS2 (Push-Pull Output)	GPIO.8	SPI Activity (Push-Pull Output)
GPIO.3	RTR Active Low (Input)	GPIO.9	SUSPEND (Push-Pull Output)
GPIO.4	Event Counter Rising Edge (Input)	GPIO.10	$\overline{\text{SUSPEND}}$ (Push-Pull Output)
GPIO.5	Clock Output (Push-Pull Output)		

The difference between an open-drain output and a push-pull output is evident when the GPIO output is driven to logic high. A logic high, open-drain output pulls the pin to the  $V_{IO}$  rail through an internal, pull-up resistor. A logic high, push-pull output directly drives the pin to the  $V_{IO}$  voltage. Open-drain outputs are typically used when interfacing to logic at a higher voltage than the  $V_{IO}$  pin. These pins can be safely pulled to the higher, external voltage through an external pull-up resistor. The maximum external pull-up voltage is 5 V.

The speed of reading and writing the GPIO pins is subject to the timing of the USB interface and host computer. GPIO pins configured as inputs or outputs are not recommended for real-time signaling.

The following paragraphs describe the alternate functions available on the corresponding GPIO pin.

### 5.1. GPIO.3—Ready-to-Read (RTR)

RTR, or Ready-to-Read, is a configurable active-low or active-high input to the CP2130 and is used by the SPI slave device to indicate to the CP2130 when to read. When performing a Read with RTR command, the CP2130 will only read SPI data when the RTR pin is asserted.

By default, GPIO.3 is configured to operate as the RTR input pin. In addition to the GPIO OTP ROM configuration, the device must be configured to use RTR flow control to use this pin.

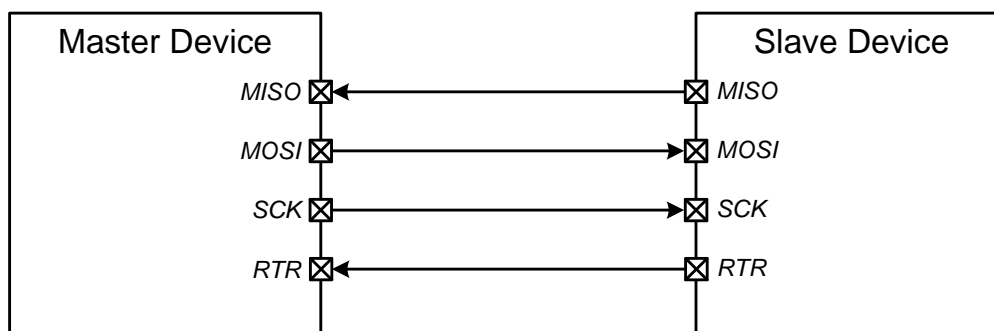


Figure 9. Hardware Flow Control Typical Connection Diagram

### 5.2. GPIO.4—Event Counter

GPIO.4 is configurable as an event counter digital input pin. The event counter can be configured to count edges or pulses. The four configurable modes are: rising edge, falling edge, positive pulse, or negative pulse. Once configured for event counter mode, the CP2130 maintains a 16-bit counter that increments by '1' whenever the specified edge or pulse is detected. The user may query the CP2130 to get the current event count. The event counter can be used to detect slave interrupt events by connecting the slave interrupt output pin to the CP2130 event counter pin.

### 5.3. GPIO.5—Clock Output

GPIO.5 is configurable to output a configurable CMOS clock output. The clock output appears at the pin at the same time the device completes enumeration and exits USB Suspend mode. The clock output is removed from the pin when the device enters USB Suspend mode. The output frequency is configurable through the use of a divider and the accuracy is specified in Table 5. When the divider is set to 0, the output frequency is 93.75 kHz. For divider values between 1 and 255, the output frequency is determined by the formula:

$$\text{GPIO.5 Clock Frequency} = \frac{24 \text{ MHz}}{\text{Divider}}$$

Equation 1. GPIO.0 Clock Output Frequency

## 5.4. GPIO.8—SPI Activity Indicator

GPIO.8 is configurable as a SPI activity indicator pin. This pin is logic high when a device is not transferring data over the SPI, and toggles at a fixed rate as specified in Table 5 when a data transfer is in progress. Typically, this pin is connected to an LED to indicate data transfer.

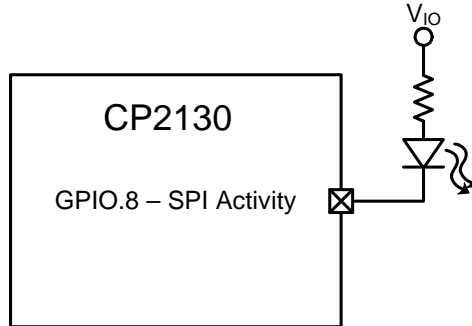


Figure 10. SPI Activity Toggle Typical Connection Diagram

## 5.5. GPIO.9-10—SUSPEND and SUSPEND

GPIO.9 and GPIO.10 are configurable as active-high SUSPEND and active-low SUSPEND pins. The SUSPEND pin is logic high when the device is in the suspended state and logic low when the device is in the active mode. The SUSPEND pin has the opposite logic value of the SUSPEND pin.

## 5.6. USB Remote Wakeup

Any of the GPIO pins may be used to trigger a USB remote wakeup event. Before the CP2130 enters the Suspend state, the device may be configured to wakeup on a port mismatch event. When any of the pins specified in the wakeup mask do not match the pin logic value specified in the wakeup value, the CP2130 will wakeup and signal remote wakeup on the bus. The CP2130 will assert USB remote wakeup signaling for 10 to 15 ms before the host may respond by resuming the CP2130.

Any GPIO pin used for remote wakeup must be configured as an input during the Suspend state. GPIO pins are selected as wakeup pins using the Wakeup Match Mask. The Wakeup Match Value specifies the logic level of the wakeup pin. When the pin level does not match the value specified, the device will wakeup. The default Wakeup Match Mask and Wakeup Match Value are shown in Table 15.

## 5.7. GPIO State During USB Suspend

All GPIO pins support programmable suspend state mode and latch values. When the CP2130 enter USB Suspend mode and the Use Suspend Mode and Values option is set, the CP2130 will reconfigure the GPIO pins just prior to entering USB Suspend mode. When the CP2130 resumes from USB Suspend mode, the GPIO pins revert to the previous function configurations and modes.



## 6. One-Time Programmable ROM

The CP2130 includes an internal, OTP ROM that may be used to customize the USB Vendor ID (VID), Product ID (PID), Manufacturer String, Product Description String, Power Descriptor, Device Release Number, Device Serial Number, GPIO configuration, Suspend Pins and Modes as desired for OEM applications. If the OTP ROM has not been customized, the default configuration data shown in Table 14 and Table 15 is used.

**Table 14. Default USB Configuration Data**

Name	Value
Vendor ID	0x10C4
Product ID	0x87A0
Power Descriptor (Attributes)	0x80 (Bus-powered)
Power Descriptor (Max. Power)	0x32 (100 mA)
Release Number	0x0100 (Release Version 01.00)
Transfer Priority	High Priority Write
Manufacturer String	"Silicon Laboratories" (62 ASCII characters maximum)
Product Description String	"CP2130 USB-to-SPI Bridge" (62 ASCII characters maximum)
Serial String	Unique 8 character ASCII string (30 ASCII characters maximum)

**Table 15. Default GPIO, UART, and Suspend Configuration Data**

Name	Value
GPIO.0	CS0 push-pull output
GPIO.1	CS1 push-pull output
GPIO.2	CS2 push-pull output
GPIO.3	RTR active low
GPIO.4	Event counter rising edge
GPIO.5	Clock output
GPIO.6	GPIO input
GPIO.7	GPIO push-pull output
GPIO.8	SPI activity push-pull output
GPIO.9	SUSPEND push-pull output
GPIO.10	SUSPEND push-pull output

Name	Value
Use Suspend Mode and Values	False
Suspend Mode	0x0000 (open-drain)
Suspend Latch	0x0000 (logic low)
Wakeup Match Mask	0x0000 (ignore all)
Wakeup Match Value	0x0000 (match value logic low)
Clock Divider	0 (93.75 kHz)

While customization of the USB configuration data is optional, customizing the VID/PID combination is strongly recommended. A unique VID/PID will prevent the device from being recognized by any other manufacturer's software application. A vendor ID can be obtained from [www.usb.org](http://www.usb.org) or Silicon Labs can provide a free PID for the OEM product that can be used with the Silicon Labs VID at [www.silabs.com/RequestPID](http://www.silabs.com/RequestPID). All CP2130 devices are pre-programmed with a unique serial number. It is important to have a unique serial string if it is possible for multiple CP2130 devices to be connected to the same PC.

Application note, "AN792: CP2130 Interface Specification", includes more information about the programmable values and their valid options. Note that certain items in the OTP ROM are programmed as a group and programming one of the items in the group prevents further programming of any of the other items in the group.

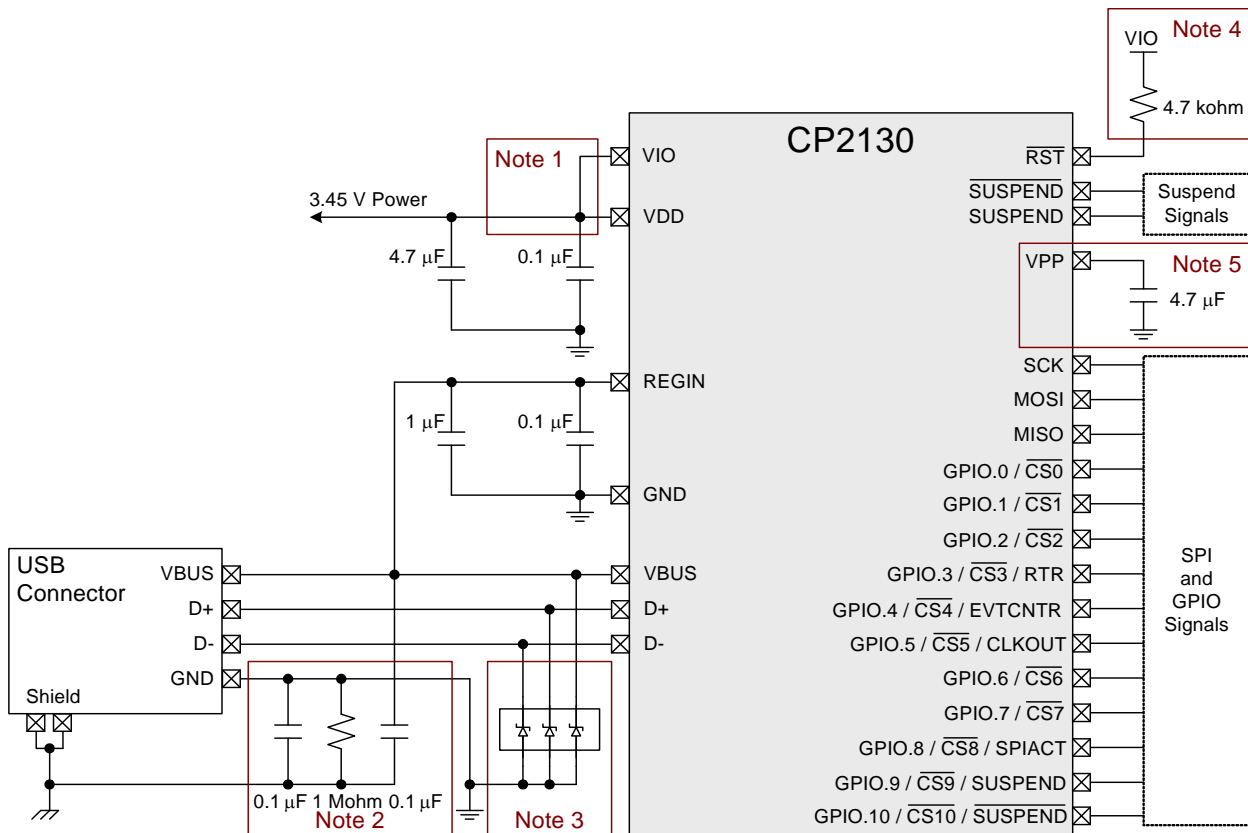
The configuration data OTP ROM is programmable by Silicon Labs prior to shipment with the desired configuration information. It can also be programmed in-system over the USB interface if a 4.7  $\mu$ F capacitor is connected between the  $V_{PP}$  pin and ground. No other circuitry should be connected to  $V_{PP}$  during a programming operation, and  $V_{IO}$  must remain at 3.3 V or higher to successfully write to the configuration OTP ROM.

## 7. Voltage Regulator

The CP2130 includes an on-chip 5 V to 3.45 V voltage regulator. This allows the CP2130 to be configured as either a USB bus-powered device or a USB self-powered device. A typical connection diagram of the device in a bus-powered application using the regulator is shown in Figure 11. When enabled, the voltage regulator output appears on the  $V_{DD}$  pin and can be used to power external devices. See Table 4 for the voltage regulator electrical characteristics.

**Note:** By default, the CP2130 is configured for bus-powered operation. The CP2130 OTP configuration must be changed if the device will be operated in either of the self-powered modes.

If the regulator is used to provide  $V_{DD}$  in a self-powered application, use the same connections from Figure 11, but connect RGIN to an on-board 5 V supply, and disconnect it from the VBUS pin. In addition, if RGIN may be unpowered while VBUS is 5 V, a resistor divider (or functionally equivalent circuit) shown in Note 6 of Figure 12 is required to meet the absolute maximum voltage on VBUS specification in Table 9.



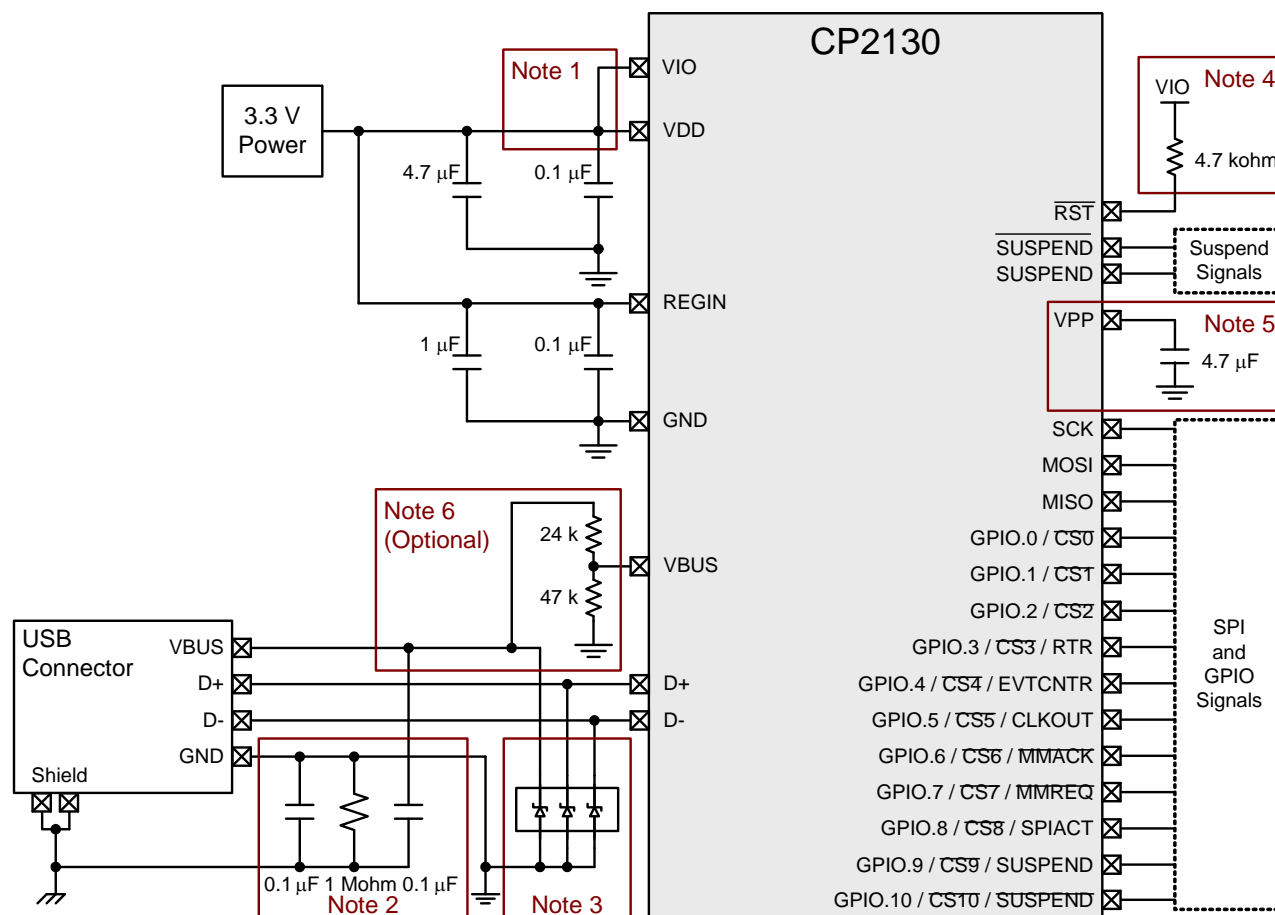
### Notes:

1. VIO can be connected directly to VDD or to a supply as low as 1.8 V to set the I/O interface voltage.
2. USB connector shield decoupling capacitors and resistor are not required, but can be added for noise immunity.
3. Avalanche transient voltage suppression diodes compatible with Full-speed USB should be added at the connector for ESD protection. Use Littelfuse p/n SP0503BAHT or equivalent.
4. An external pull-up is not required, but can be added for noise immunity.
5. If programming the configuration ROM via USB, add a 4.7 μF capacitor between VPP and ground.  
During a programming operation, do not connect the VPP pin to other circuitry, and ensure that VIO is at least 3.3 V.

**Figure 11. Typical Bus-Powered Connection Diagram**

Alternatively, if 3.0 to 3.6 V power is supplied to the V<sub>DD</sub> pin, the CP2130 can function as a USB self-powered device with the voltage regulator bypassed. For this configuration, tie the REGIN input to V<sub>DD</sub> to bypass the voltage regulator. A typical connection diagram showing the device in a self-powered application with the regulator bypassed is shown in Figure 12.

The USB max power and power attributes descriptor must match the device power usage and configuration. See application note, “AN721: CP21xx Customization Guide”, for information on how to customize USB descriptors for the CP2130.



**Notes:**

1. VIO can be connected directly to VDD or to a supply as low as 1.8 V to set the I/O interface voltage.
2. USB connector shield decoupling capacitors and resistor are not required, but can be added for noise immunity.
3. Avalanche transient voltage suppression diodes compatible with Full-speed USB should be added at the connector for ESD protection. Use Littelfuse p/n SP0503BAHT or equivalent.
4. An external pull-up is not required, but can be added for noise immunity.
5. If programming the configuration ROM via USB, add a 4.7 µF capacitor between VPP and ground.  
During a programming operation, do not connect the VPP pin to other circuitry, and ensure that VIO is at least 3.3 V.
6. For self-powered systems where VDD and VIO may be unpowered when VBUS is connected to 5 V, a resistor divider (or functionally-equivalent circuit) on VBUS is required to meet the absolute maximum voltage on VBUS specification in the Electrical Characteristics section.

**Figure 12. Typical Self-Powered Connection Diagram (Regulator Bypass)**

## 8. CP2130 Interface Specification and Windows Interface DLL

The CP2130 is a Bulk Mode USB device and requires a generic USB driver such as Microsoft's WinUSB driver or the open-source LibUSB driver. The CP2130 uses a vendor-specific interface protocol, and so the host application or library must comply with the CP2130 Interface Specification to communicate with the device. The low-level USB specification for the CP2130 is provided in application note, "AN792: CP2130 Interface Specification." This document describes all of the basic functions for opening, reading from, writing to, and closing the device as well as the OTP ROM programming functions.

Silicon Labs also provides an interface library that encapsulates the CP2130 interface and also adds higher level features such as read/write time-outs. This library is the recommended interface for the CP2130. The interface library is provided as a Windows DLL. Documentation for the interface library API is included in the installation package.

AN792: CP2130 Interface Specification and the library are available in the CP2130EK CD as well as online at: [www.silabs.com](http://www.silabs.com).

## 9. Relevant Application Notes

The following application notes are applicable to the CP2130. The latest versions of these application notes and their accompanying software are available at <http://www.silabs.com/products/Interface/Pages/interface-application-notes.aspx>.

- **AN721: CP21xx Device Customization Guide.** This application note describes how to use the AN721 software, CP21xx Customization Utility, to configure the USB parameters on CP2130 devices.
- **AN792: CP2130 Interface Specification.** This application note describes how to interface to the CP2130 using the low-level, USB bulk and control mode Interface.

10. Pin Descriptions

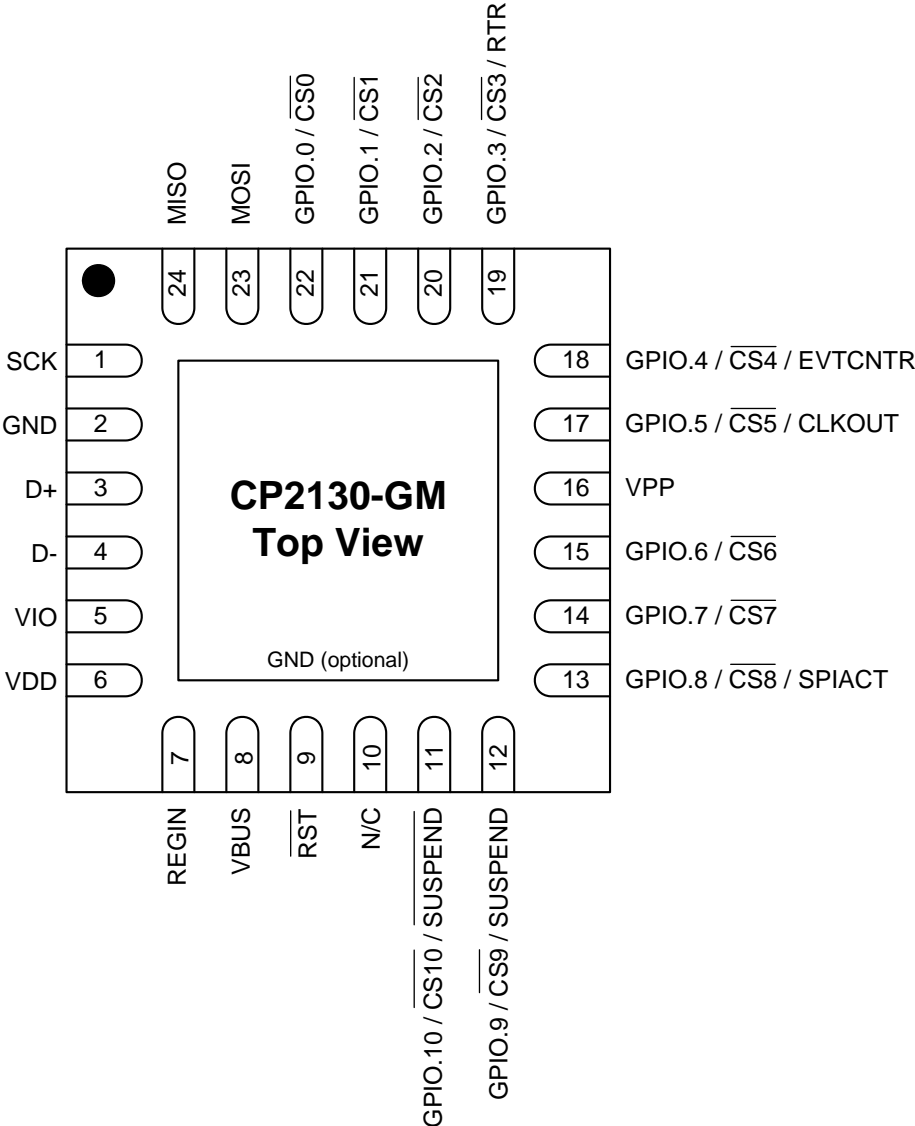


Figure 13. QFN-24 Pinout Diagram (Top View)

**Table 16. CP2130 Pin Definitions**

Pin #	Name	Type	Description
1	SCK	D Out	SPI clock output
2	GND		Ground. Must be tied to ground.
3	D+	D I/O	USB D+
4	D-	D I/O	USB D-
5	V <sub>IO</sub>	Power In	I/O Supply Voltage Input.
6	V <sub>DD</sub>	Power In	Power Supply Voltage Input.
		Power Out	Voltage Regulator Output. See Section 7.
7	REGIN	Power In	5 V Regulator Input. This pin is the input to the on-chip voltage regulator.
8	VBUS	D In	VBUS Sense Input. This pin should be connected to the VBUS signal of a USB network.
9	$\overline{\text{RST}}$	D I/O	Device Reset. Open-drain output of internal power-on reset or V <sub>DD</sub> monitor. An external source can initiate a system reset by driving this pin low for the time specified in Table 3.
10*	N/C		No connect. This pin should be left unconnected or tied to V <sub>IO</sub> .
11*	GPIO.10	D I/O	In GPIO mode, this pin is a user-configurable input or output.
	$\overline{\text{CS10}}$	D Out	In chip select mode, this pin is a SPI chip select output.
	$\overline{\text{SUSPEND}}$	D Out	In USB suspend mode, this pin is Low when in USB suspend mode.
12*	GPIO.9	D I/O	In GPIO mode, this pin is a user-configurable input or output.
	$\overline{\text{CS9}}$	D Out	In chip select mode, this pin is a SPI chip select output.
	SUSPEND	D Out	In USB suspend mode, this pin is High when in USB suspend mode.
13*	GPIO.8	D I/O	In GPIO mode, this pin is a user-configurable input or output.
	$\overline{\text{CS8}}$	D Out	In chip select mode, this pin is a SPI chip select output.
	SPIACT	D Out	In SPI activity mode, this pin toggles to indicate SPI activity.
14*	GPIO.7	D I/O	In GPIO mode, this pin is a user-configurable input or output.
	$\overline{\text{CS7}}$	D Out	In chip select mode, this pin is a SPI chip select output.
15*	GPIO.6	D I/O	In GPIO mode, this pin is a user-configurable input or output.
	$\overline{\text{CS6}}$	D Out	In chip select mode, this pin is a SPI chip select output.
16*	V <sub>PP</sub>	Special	Connect a 4.7 $\mu\text{F}$ capacitor between this pin and ground to support OTP ROM programming via the USB interface.

**\*Note:** Pin can be left unconnected when not in use.

Table 16. CP2130 Pin Definitions (Continued)

Pin #	Name	Type	Description
17*	GPIO.5	D I/O	In GPIO mode, this pin is a user-configurable input or output.
	$\overline{\text{CS5}}$	D Out	In chip select mode, this pin is a SPI chip select output.
	CLKOUT	D Out	In clock output mode, this pin outputs a configurable frequency clock signal.
18*	GPIO.4	D I/O	In GPIO mode, this pin is a user-configurable input or output.
	$\overline{\text{CS4}}$	D Out	In chip select mode, this pin is a SPI chip select output.
	EVTCNTR	D In	In event counter mode, this pin is an event counter input.
19*	GPIO.3	D I/O	In GPIO mode, this pin is a user-configurable input or output.
	$\overline{\text{CS3}}$	D Out	In chip select mode, this pin is a SPI chip select output.
	RTR	D In	In Ready-to-Read mode, this pin is a SPI read flow control input.
20*	GPIO.2	D I/O	In GPIO mode, this pin is a user-configurable input or output.
	$\overline{\text{CS2}}$	D Out	In chip select mode, this pin is a SPI chip select output.
21*	GPIO.1	D I/O	In GPIO mode, this pin is a user-configurable input or output.
	$\overline{\text{CS1}}$	D Out	In chip select mode, this pin is a SPI chip select output.
22*	GPIO.0	D I/O	In GPIO mode, this pin is a user-configurable input or output.
	$\overline{\text{CS0}}$	D Out	In chip select mode, this pin is a SPI chip select output.
23	MOSI	D Out	SPI master output/slave input
24	MISO	D In	SPI master input/slave output
<b>*Note:</b> Pin can be left unconnected when not in use.			

11. QFN-24 Package Specifications

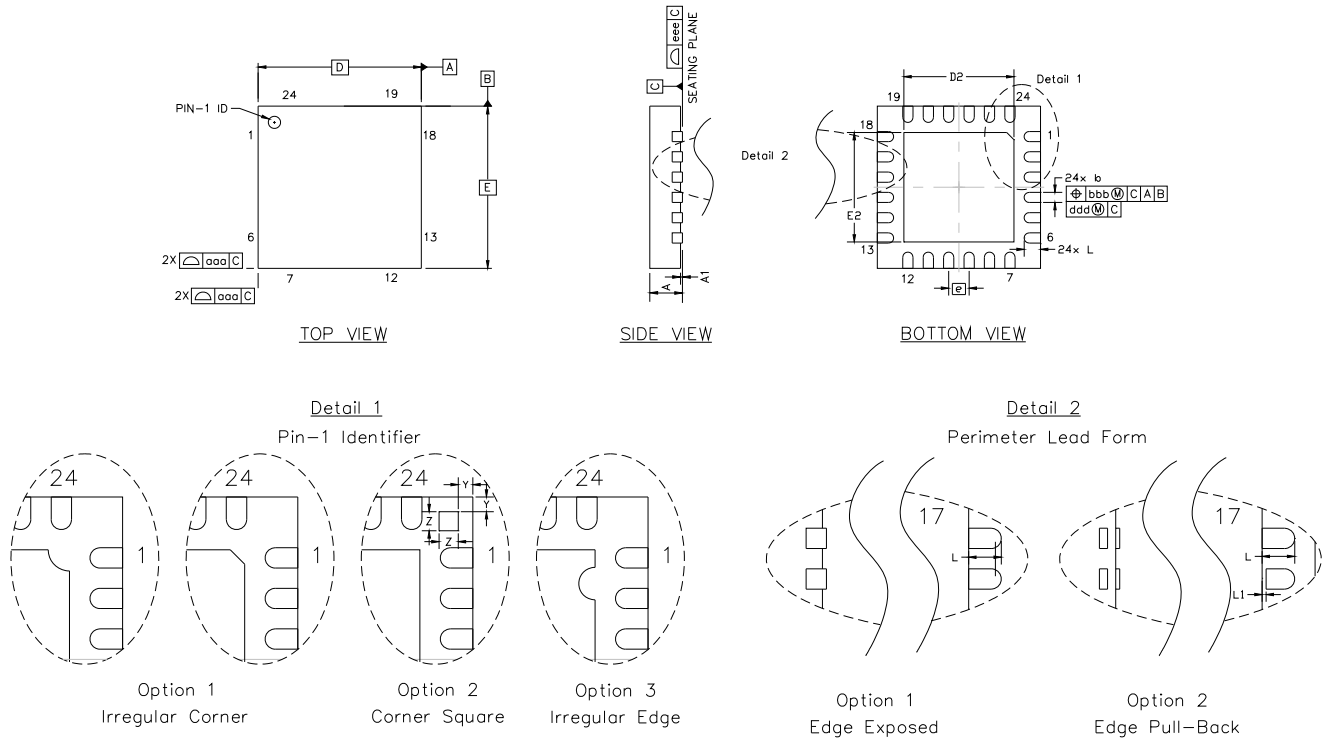


Figure 14. QFN-24 Package Drawing

Table 17. QFN-24 Package Dimensions

Dimension	Min	Typ	Max
A	0.70	0.75	0.80
A1	0.00	0.02	0.05
b	0.18	0.25	0.30
D	4.00 BSC.		
D2	2.55	2.70	2.80
e	0.50 BSC.		
E	4.00 BSC.		
E2	2.55	2.70	2.80
L	0.30	0.40	0.50
L1	0.00	—	0.15
aaa	—	—	0.15
bbb	—	—	0.10
ddd	—	—	0.05
eee	—	—	0.08
Z	—	0.24	—
Y	—	0.18	—

Notes:

1. All dimensions shown are in millimeters (mm) unless otherwise noted.
2. Dimensioning and Tolerancing per ANSI Y14.5M-1994.
3. This drawing conforms to JEDEC Solid State Outline MO-220, variation WGGD except for custom features D2, E2, Z, Y, and L which are toleranced per supplier designation.
4. Recommended card reflow profile is per the JEDEC/IPC J-STD-020 specification for Small Body Components.



## 12. PCB Land Pattern

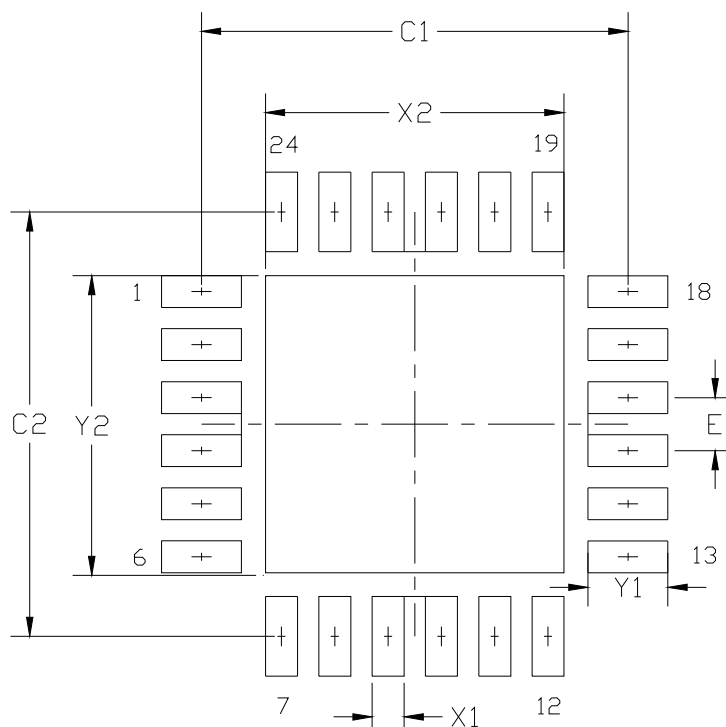


Figure 15. QFN-24 Recommended PCB Land Pattern

Table 18. QFN-24 PCB Land Pattern Dimensions

Dimension	Min	Max	Dimension	Min	Max
C1	3.90	4.00	X2	2.70	2.80
C2	3.90	4.00	Y1	0.65	0.75
E	0.50 BSC		Y2	2.70	2.80
X1	0.20	0.30			

**Notes:**

**General**

- All dimensions shown are in millimeters (mm) unless otherwise noted.
- This Land Pattern Design is based on the IPC-7351 guidelines.

**Solder Mask Design**

- All metal pads are to be non-solder mask defined (NSMD). Clearance between the solder mask and the metal pad is to be 60  $\mu\text{m}$  minimum, all the way around the pad.

**Stencil Design**

- A stainless steel, laser-cut and electro-polished stencil with trapezoidal walls should be used to assure good solder paste release.
- The stencil thickness should be 0.125 mm (5 mils).
- The ratio of stencil aperture to land pad size should be 1:1 for all perimeter pads.
- A 2 x 2 array of 1.10 x 1.10 mm openings on a 1.30 mm pitch should be used for the center pad.

**Card Assembly**

- A No-Clean, Type-3 solder paste is recommended.
- The recommended card reflow profile is per the JEDEC/IPC J-STD-020 specification for Small Body Components.

## DOCUMENT CHANGE LIST

### Revision 0.5 to Revision 0.6

- Updated pin configuration functions for GPIO.6 and GPIO.7.

### Revision 0.6 to Revision 0.7

- Moved VBUS to a separate row and updated the specification in Table 9, "Absolute Maximum Ratings\*," on page 8.
- Added  $V_{PP}$  Voltage specification to Table 7, "OTP ROM Electrical Characteristics," on page 7.
- Updated "7. Voltage Regulator" on page 18 to add absolute maximum voltage on VBUS requirements in self-powered systems.
- Updated measured throughput numbers in Table 10, "Typical SPI Throughput," on page 11.

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